IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and N	ials and Mfg Information			
upplier Inforn	nation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi											2024-0	2024-04-19			
Contact Name			Title - Contact			1	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stew	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repres	entative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env-Stew	ards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Request	er Item Number	Mfr Item Number Mfr Item Name FSUSB242UCX TYPE C USB PROT		Mfr Item Name			Effective Dat	e Vers	ion	Manufacturing Site		Weight*	UOM	Unit Type	
				TECT SWIT	ГСН	2024-04-19	PBB			1.935	mg	Each			
Ianufacturing	Process Informati	ion						·					,		
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Tem		ly Temperatu	rature Max Time at Peak Ten		ture Numb	per of Reflow Cyc	eles		
SnAgCu			CU Alloy 1				260 C 30			seconds 3					
omments															
vel 1 - maximum	time at peak temperatui	re during sol	dering is 10-3	30 seconds											
or more informati	on regarding material c	composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Backside Protection Film	0.058	mg		Epoxy resin	proprietary data		0.0121	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0011	mg
			Supplier	Acrylic resins	Proprietary Data		0.0121	mg
			Supplier	Silica (SiO2)	14464-46-1		0.0327	mg
Die	1.303	mg	Supplier	Silicon (Si)	7440-21-3		1.2954	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0076	mg
Solder Ball	0.548	mg	Supplier	Silver (Ag)	7440-22-4		0.031	mg
			Supplier	Tin (Sn)	7440-31-5		0.5137	mg
			Supplier	Copper (Cu)	7440-50-8		0.0033	mg
Under Bump Metal	0.026	mg	Supplier	Titanium (Ti)	7440-32-6		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.0258	mg